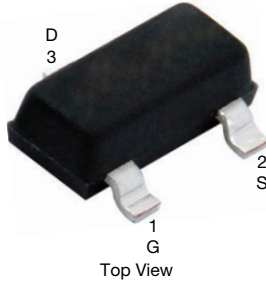


## P-Channel 30 V (D-S) MOSFET

**SOT-23 (TO-236)**

**Marking code: G6**

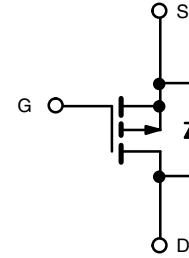
| PRODUCT SUMMARY                                    |        |
|--|--------|
| $V_{DS}$ (V)                                       | -30    |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10$ V  | 0.0227 |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5$ V | 0.0330 |
| $Q_g$ typ. (nC)                                    | 8.2    |
| $I_D$ (A) <sup>a, e</sup>                          | -7.5   |
| Configuration                                      | Single |

**FEATURES**

- TrenchFET<sup>®</sup> Gen IV p-channel power MOSFET
- 100 %  $R_g$  and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**
**APPLICATIONS**

- Load switch
- Circuit protection
- Motor drive control



P-Channel MOSFET

| ORDERING INFORMATION            |                 |
|---------------------------------|-----------------|
| Package                         | SOT-23          |
| Lead (Pb)-free and halogen-free | Si2393DS-T1-GE3 |

| ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted) |               |                |                      |      |
|---|---------------|----------------|----------------------|------|
| PARAMETER   |               | SYMBOL         | LIMIT                | UNIT |
| Drain-source voltage  |               | $V_{DS}$       | -30                  | V    |
| Gate-source voltage   |               | $V_{GS}$       | -20 / +16            |      |
| Continuous drain current ( $T_J = 150$ °C)                        | $T_C = 25$ °C | $I_D$          | -7.5 <sup>e</sup>    | A    |
|   | $T_C = 70$ °C |                | -6.9                 |      |
|   | $T_A = 25$ °C |                | -6.1 <sup>b, c</sup> |      |
|   | $T_A = 70$ °C |                | -4.8 <sup>b, c</sup> |      |
| Pulsed drain current ( $t = 100$ $\mu$ s)                         |               | $I_{DM}$       | -50                  |      |
| Continuous source-drain diode current                             | $T_C = 25$ °C | $I_S$          | -2.1                 |      |
|   | $T_A = 25$ °C |                | -1.1 <sup>b, c</sup> |      |
| Maximum power dissipation   | $T_C = 25$ °C | $P_D$          | 2.5                  | W    |
|   | $T_C = 70$ °C |                | 1.6                  |      |
|   | $T_A = 25$ °C |                | 1.3 <sup>b, c</sup>  |      |
|   | $T_A = 70$ °C |                | 0.8 <sup>b, c</sup>  |      |
| Operating junction and storage temperature range                  |               | $T_J, T_{stg}$ | -55 to +150          | °C   |

| THERMAL RESISTANCE RATINGS               |              |            |         |         |      |
|--|--------------|------------|---------|---------|------|
| PARAMETER                                |              | SYMBOL     | TYPICAL | MAXIMUM | UNIT |
| Maximum junction-to-ambient <sup>b</sup> | $t \leq 5$ s | $R_{thJA}$ | 75      | 100     | °C/W |
| Maximum junction-to-case (drain)         | Steady state | $R_{thJF}$ | 40      | 50      |      |

**Notes**

- Based on  $T_C = 25$  °C
- Surface mounted on 1" x 1" FR4 board
- $t = 5$  s
- Maximum under steady state conditions is 166 °C/W
- Package limited

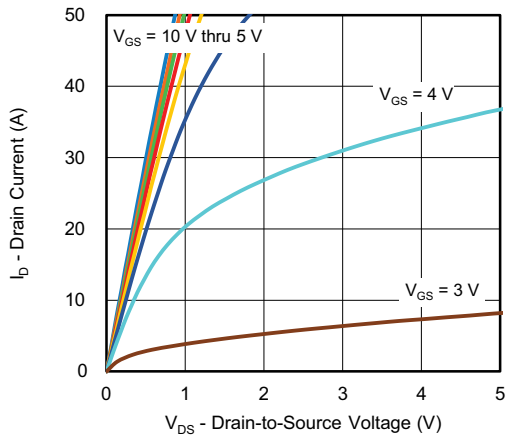
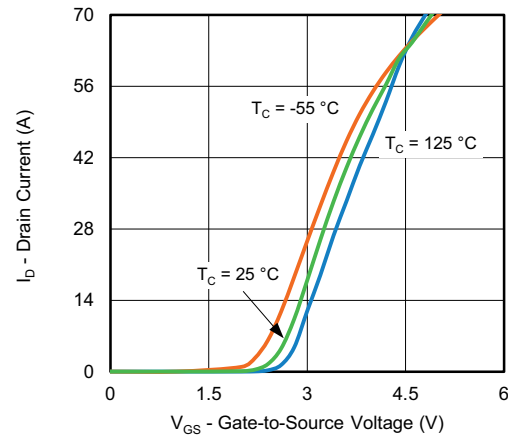
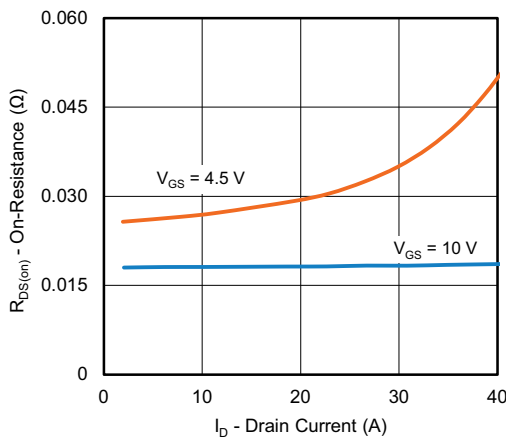
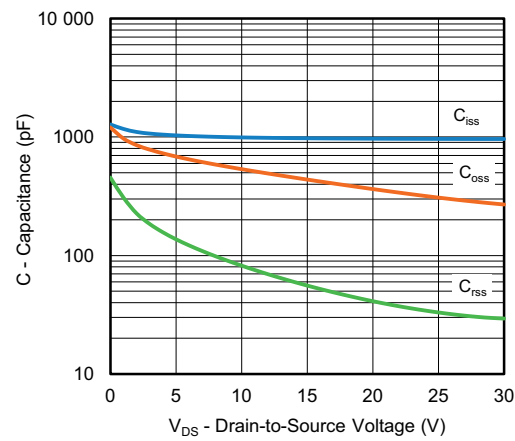
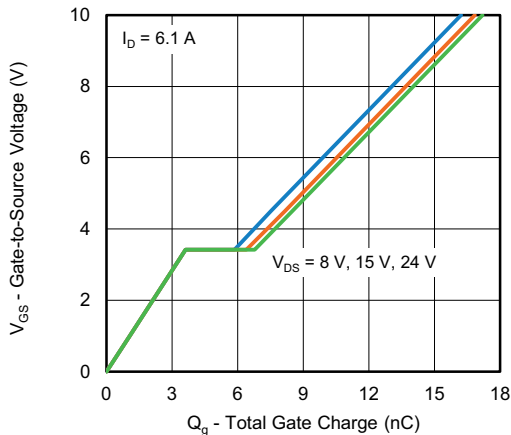
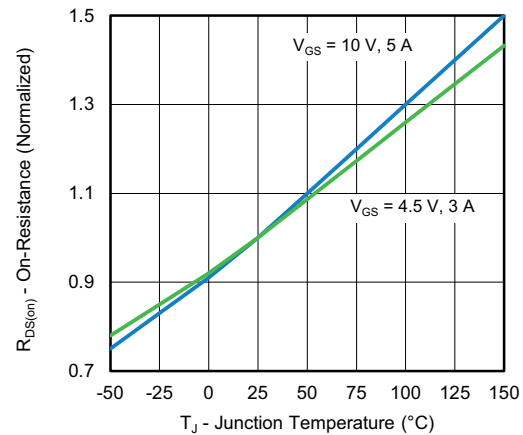


| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted) |                                      |   |      |        |        |       |
|---|--------------------------------------|---|------|--------|--------|-------|
| PARAMETER   | SYMBOL                               | TEST CONDITIONS   | MIN. | TYP.   | MAX.   | UNIT  |
| <b>Static</b>   |                                      |   |      |        |        |       |
| Drain-source breakdown voltage                                  | V <sub>DS</sub>                      | V <sub>GS</sub> = 0 V, I <sub>D</sub> = -250 μA   | -30  | -      | -      | V     |
| V <sub>DS</sub> temperature coefficient                         | ΔV <sub>DS</sub> /T <sub>J</sub>     | I <sub>D</sub> = -250 μA  | -    | -24.7  | -      | mV/°C |
| V <sub>GS(th)</sub> temperature coefficient                     | ΔV <sub>GS(th)</sub> /T <sub>J</sub> | I <sub>D</sub> = -250 μA  | -    | 5.7    | -      |       |
| Gate-source threshold voltage                                   | V <sub>GS(th)</sub>                  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA   | -1   | -      | -2.2   | V     |
| Gate-source leakage   | I <sub>GSS</sub>                     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = -20 V / +16 V  | -    | -      | 100    | nA    |
| Zero gate voltage drain current                                 | I <sub>DSS</sub>                     | V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V  | -    | -      | -1     | μA    |
|   |                                      | V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C  | -    | -      | -15    |       |
| On-state drain current <sup>a</sup>                             | I <sub>D(on)</sub>                   | V <sub>DS</sub> ≥ -10 V, V <sub>GS</sub> = -10 V  | -10  | -      | -      | A     |
| Drain-source on-state resistance <sup>a</sup>                   | R <sub>DS(on)</sub>                  | V <sub>GS</sub> = -10 V, I <sub>D</sub> = -5 A  | -    | 0.0189 | 0.0227 | Ω     |
|   |                                      | V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -3 A   | -    | 0.0264 | 0.0330 |       |
| Forward transconductance <sup>a</sup>                           | g <sub>fs</sub>                      | V <sub>DS</sub> = -15 V, I <sub>D</sub> = -5 A  | -    | 10     | -      | S     |
| <b>Dynamic <sup>b</sup></b>                                     |                                      |   |      |        |        |       |
| Input capacitance   | C <sub>ISS</sub>                     | V <sub>DS</sub> = -15 V, V <sub>GS</sub> = 0 V, f = 1 MHz   | -    | 980    | -      | pF    |
| Output capacitance  | C <sub>OSS</sub>                     |   | -    | 440    | -      |       |
| Reverse transfer capacitance                                    | C <sub>RSS</sub>                     |   | -    | 55     | -      |       |
| Total gate charge   | Q <sub>g</sub>                       | V <sub>DS</sub> = -15 V, V <sub>GS</sub> = -10 V, I <sub>D</sub> = -6.1 A   | -    | 16.8   | 25.2   | nC    |
|   |                                      | V <sub>DS</sub> = -15 V, V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -6.1 A  | -    | 8.2    | 12.3   |       |
| Gate-source charge  | Q <sub>gs</sub>                      |   | -    | 3.6    | -      |       |
| Gate-drain charge   | Q <sub>gd</sub>                      |   | -    | 2.8    | -      |       |
| Gate resistance   | R <sub>g</sub>                       | f = 1 MHz   | 3.6  | 18.3   | 36.6   | Ω     |
| Turn-on delay time  | t <sub>d(on)</sub>                   | V <sub>DD</sub> = -15 V, R <sub>L</sub> = 2.5 Ω, I <sub>D</sub> ≅ -4.8 A, V <sub>GEN</sub> = -10 V, R <sub>g</sub> = 1 Ω  | -    | 14     | 28     | ns    |
| Rise time   | t <sub>r</sub>                       |   | -    | 8      | 16     |       |
| Turn-off delay time   | t <sub>d(off)</sub>                  |   | -    | 48     | 96     |       |
| Fall time   | t <sub>f</sub>                       |   | -    | 32     | 64     |       |
| Turn-on delay time  | t <sub>d(on)</sub>                   | V <sub>DD</sub> = -15 V, R <sub>L</sub> = 2.5 Ω, I <sub>D</sub> ≅ -4.8 A, V <sub>GEN</sub> = -4.5 V, R <sub>g</sub> = 1 Ω | -    | 30     | 45     |       |
| Rise time   | t <sub>r</sub>                       |   | -    | 85     | 170    |       |
| Turn-off delay time   | t <sub>d(off)</sub>                  |   | -    | 34     | 68     |       |
| Fall time   | t <sub>f</sub>                       |   | -    | 40     | 80     |       |
| <b>Drain-Source Body Diode Characteristics</b>                  |                                      |   |      |        |        |       |
| Continuous source-drain diode current                           | I <sub>S</sub>                       | T <sub>C</sub> = 25 °C  | -    | -      | -2.1   | A     |
| Pulse diode forward current                                     | I <sub>SM</sub>                      |   | -    | -      | -50    |       |
| Body diode voltage  | V <sub>SD</sub>                      | I <sub>S</sub> = -4.8 A, V <sub>GS</sub> = 0 V  | -    | -0.8   | -1.2   | V     |
| Body diode reverse recovery time                                | t <sub>rr</sub>                      | I <sub>F</sub> = -4.8 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C   | -    | 21     | 42     | ns    |
| Body diode reverse recovery charge                              | Q <sub>rr</sub>                      |   | -    | 8      | 16     | nC    |
| Reverse recovery fall time                                      | t <sub>a</sub>                       |   | -    | 8.5    | -      | ns    |
| Reverse recovery rise time                                      | t <sub>b</sub>                       |   | -    | 12.5   | -      |       |

**Notes**

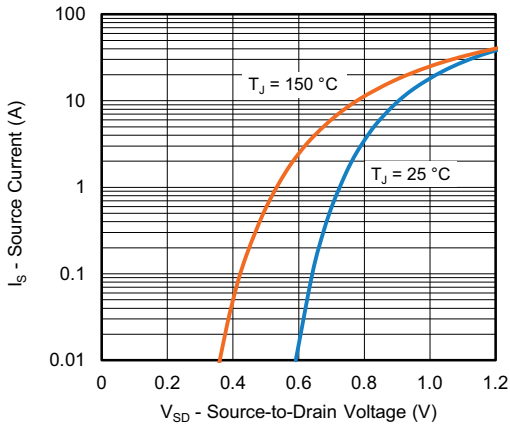
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

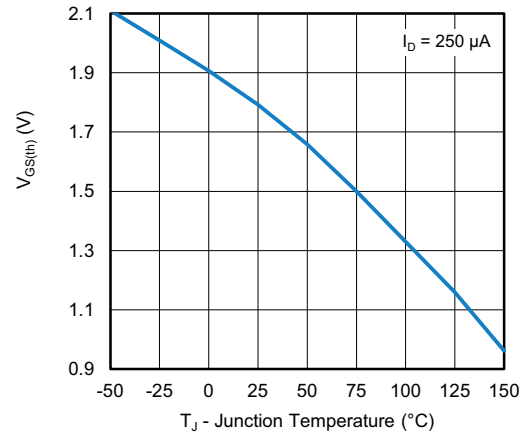
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current and Gate Voltage**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**



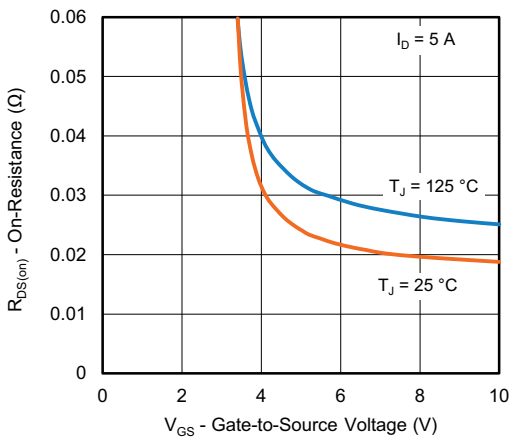
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



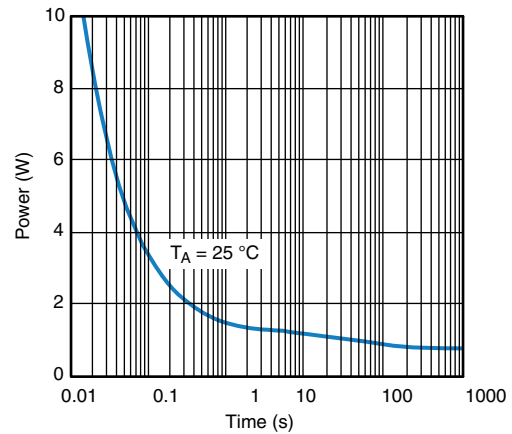
Source-Drain Diode Forward Voltage



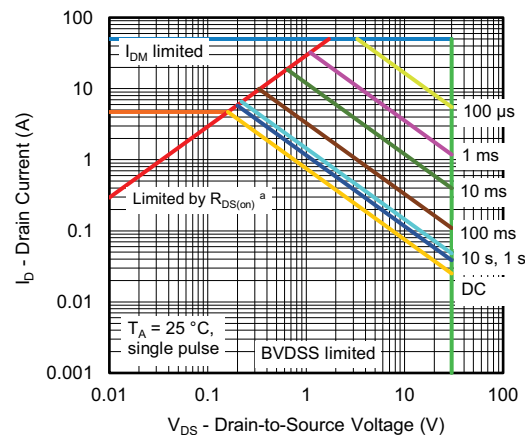
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



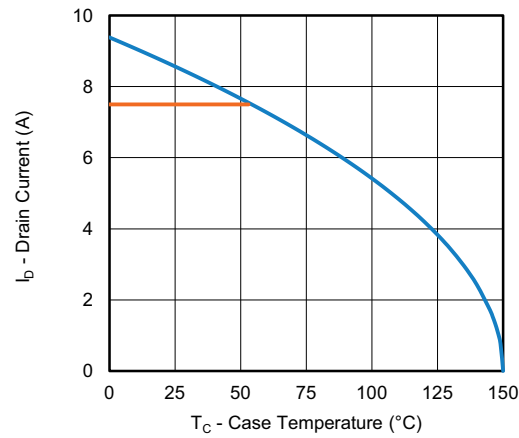
Safe Operating Area, Junction-to-Ambient

Note

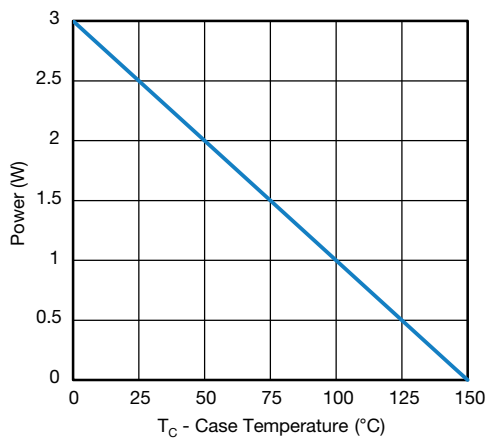
a. VGS > minimum VGS at which RDS(on) is specified



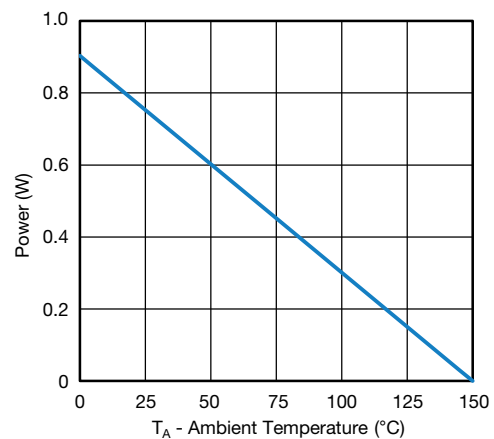
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating <sup>a</sup>**



**Power, Junction-to-Case**



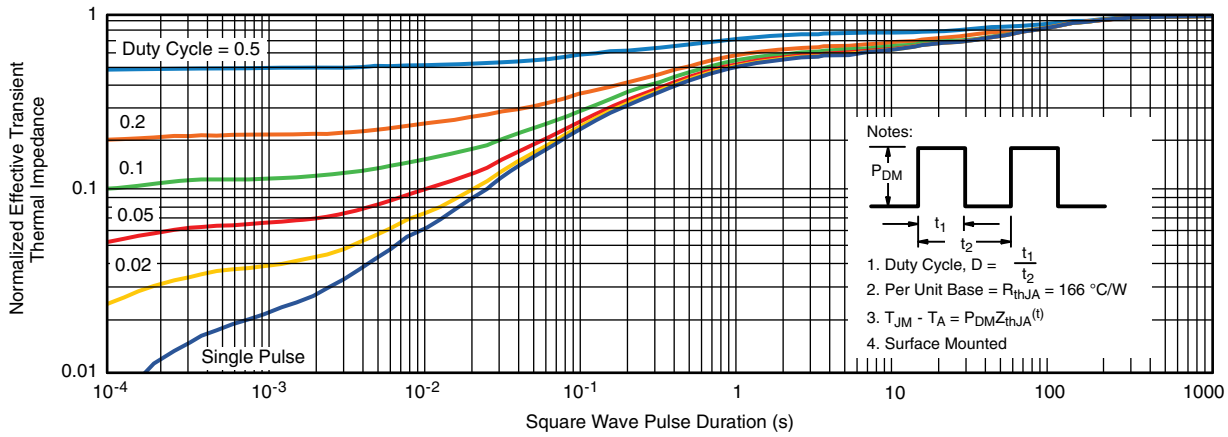
**Power, Junction-to-Ambient**

**Note**

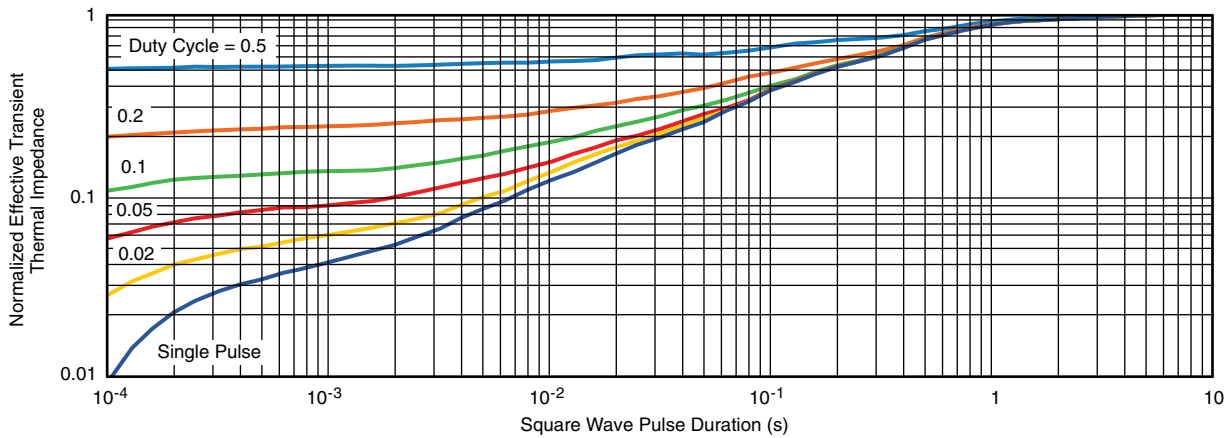
- a. The power dissipation  $P_D$  is based on  $T_J \text{ max.} = 150 \text{ }^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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## SOT-23 (TO-236): 3-LEAD

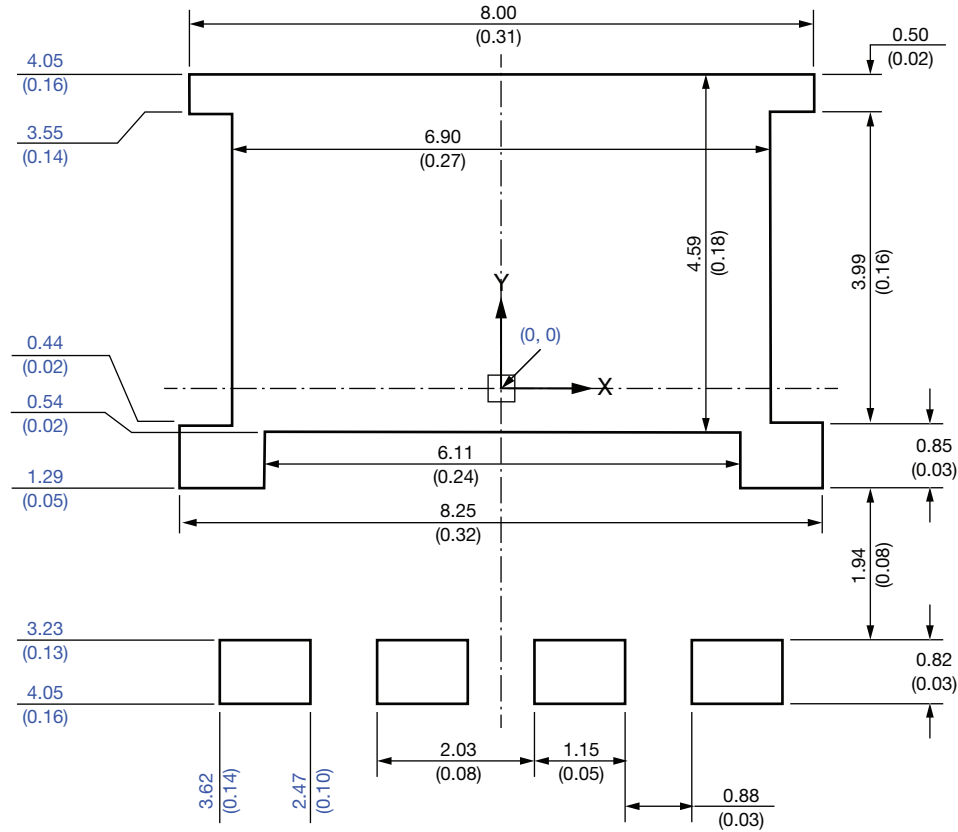


| Dim            | MILLIMETERS |      | INCHES     |       |
|----------------|-------------|------|------------|-------|
|                | Min         | Max  | Min        | Max   |
| A              | 0.89        | 1.12 | 0.035      | 0.044 |
| A <sub>1</sub> | 0.01        | 0.10 | 0.0004     | 0.004 |
| A <sub>2</sub> | 0.88        | 1.02 | 0.0346     | 0.040 |
| b              | 0.35        | 0.50 | 0.014      | 0.020 |
| c              | 0.085       | 0.18 | 0.003      | 0.007 |
| D              | 2.80        | 3.04 | 0.110      | 0.120 |
| E              | 2.10        | 2.64 | 0.083      | 0.104 |
| E <sub>1</sub> | 1.20        | 1.40 | 0.047      | 0.055 |
| e              | 0.95 BSC    |      | 0.0374 Ref |       |
| e <sub>1</sub> | 1.90 BSC    |      | 0.0748 Ref |       |
| L              | 0.40        | 0.60 | 0.016      | 0.024 |
| L <sub>1</sub> | 0.64 Ref    |      | 0.025 Ref  |       |
| S              | 0.50 Ref    |      | 0.020 Ref  |       |
| q              | 3°          | 8°   | 3°         | 8°    |

ECN: S-03946-Rev. K, 09-Jul-01  
 DWG: 5479



# Recommended Minimum PADS for PowerPAK® 8 x 8L Single



Dimensions in millimeters (inches)

**Note**

- Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.





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